

<b>Notice of References Cited</b>		Application/Control No. 09/652,216	Applicant(s)/Patent Under Reexamination JIANG ET AL.	
		Examiner Evan T. Pert	Art Unit 2829	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A	US-2002/0055246 A1	12-2001	Jiang et al.	438/597
B	US-6,406,938	06-2002	Rodenbeck et al.	438/108
C	US-6,081,267	05-2000	Houston, Theodore W.	365/154
D	US-6,084,116	05-2000	Akram, Salman	257/700
E	US-5,317,107	05-1994	Osorio, Rolando J.	174/35R
F	US-			
G	US-			
H	US-			
I	US-			
J	US-			
K	US-			
L	US-			
M	US-			

**FOREIGN PATENT DOCUMENTS**

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
N					
O					
P					
Q					
R					
S					
T					

**NON-PATENT DOCUMENTS**

*	Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
U	Shah et al., "Cyanate Ester Die Attach Material For Radiation Hardened Electronic Packages", 3rd International Conference on Adhesive Joining & Coating Technology in Electronic Manufacturing, Binghamton, NY, September 1998., 6 pages.
V	
W	
X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.